

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT	
NATURE OF CONVEYANCE:	ASSIGNMENT	
CONVEYING PARTY DATA		
	Name	Execution Date
	SURAJ RAVI MUSUVATHY	01/06/2015
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	Property Type	Number
	Application Number:	14591320
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NAME OF SUBMITTER:	SUSAN HENDERSON	
SIGNATURE:	/Susan Henderson/	
DATE SIGNED:	02/23/2015	
Total Attachments: 2		
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ASSIGNMENT

For good and valuable consideration, I (We),
Suraj Ravi Musuvathy, residing at 15 Quincy Road, Glenmont, NY 12077, US, citizen of IN

hereafter individually or collectively referred to as "Assignor(s)";

Hereby, (I) acknowledge having previously assigned, sold and transferred to **Siemens Corporation**, a corporation organized and existing under the laws of UNITED STATES OF AMERICA, having its principal place of business at 170 Wood Avenue South, Iselin, New Jersey, 08830, hereinafter "Assignee", its successors, assigns and legal representatives, or to a predecessor of Assignee, pursuant to (A)(i) the laws of UNITED STATES OF AMERICA or (ii) a Patent & Secrecy Agreement or similar legal document such as, without limitation, an employee agreement executed at the time of entering into the employment of, or executed as a condition of continuing employment with, the Assignee or a predecessor of the Assignee, the entire right, (including any and all priority rights, and the right to sue and recover damages for past, present and future infringement) title and interest, in and for the United States and all foreign countries, in and to any and all inventions or improvements which are disclosed in an invention disclosure and/or in the below-identified documents currently filed with this Assignment, already filed or granted for Letters Patent (in which case, any provision of the subject Assignment that is in conflict with or is in addition to any provision in the prior agreement(s) or assignment(s) then this Assignment shall govern, take precedence, and be of legal effect), or

(B)(i) to the extent such laws of UNITED STATES OF AMERICA or such Patent & Secrecy Agreement or similar legal document failed or fails, in whole or part, to have assigned, sold or transferred the entire right (including priority rights), title and interest, in and for the United States and all foreign countries, in and to all inventions or improvements which are disclosed in the below-identified application(s) or pending application(s) or granted Letters Patent, or (ii) if no such agreement(s) exist assigning, selling or transferring any such right (including priority rights), title or interest; then for good and valuable consideration, Assignor(s) now and hereby, effective Nunc Pro Tunc on the filing date of the below identified patent application(s), pending patent application(s) or granted Letter Patent(s), assign, sell and transfer(s) to Assignee, its successors, assigns and legal representatives, the entire right, (including all priority rights), title and interest in and for the United States and all foreign countries, in and to any and all inventions and/or improvements which are disclosed in the following identified; patent application(s), pending patent application(s) or granted Letter Patent(s)

Patent Application Title: **Method for Creating Three Dimensional Lattice Structures in Computer-Aided Design Models for Additive Manufacturing**
Internal Case Number(s): 2014P00366 US01

Patent Application Title: **Method for Creating Three Dimensional Lattice Structures in Computer-Aided Design Models for Additive Manufacturing**
Filing Date (MM/DD/YYYY): 01/09/2014
Filing Number: 61/925,362
Internal Case Number(s): 2014P00366 US

and in and to said application(s) or granted patents and all applications claiming priority to said application or granted patent, including, without limitation, and all divisional, continuing, substitute, renewal, reissue, and all other applications for Letters Patent which have been or shall be filed in the United States and all foreign countries on any of the inventions and/or improvements; and in

and to all original and reissued patents which have been or shall be filed in the United States and all foreign countries on the inventions and/or improvements;

(II) Agree that said Assignee may apply for and receive Letters Patent for said inventions and/or improvements in its own name; and that, when requested, without charge to but at the expense of said Assignee, its successors, assigns and legal representatives, to carry out in good faith the intent and purpose of this assignment, the undersigned will execute all divisional, continuing, substitute, renewal, reissue, and all other patent applications on any and all said inventions and/or improvements; execute all rightful oaths, assignments, powers of attorney and other papers; communicate to said Assignee, its successors, assigns, and legal representatives, all facts known to the undersigned relating to said inventions and/or improvements and the history thereof; and generally do everything possible which said Assignee, its successors, assigns or legal representatives shall consider desirable for aiding in securing and maintaining proper patent protection for said inventions and/or improvements and for vesting title to said inventions and/or improvements and all applications for patents and all patents on said inventions and/or improvements, in said Assignee, its successors, assigns and legal representatives; and

(III) Covenant with said Assignee, its successors, assigns and legal representatives that no assignment, grant, mortgage, license or other agreement affecting the rights and property herein conveyed has been made to others by the undersigned, and that full right to convey the same as herein expressed is possessed by the undersigned.



Witness Signature

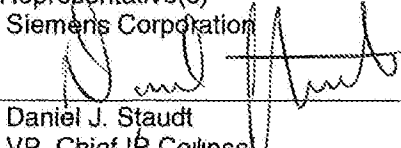


Suraj Ravi Musuvathy

Sanjeer Srivastava
printed name

01/06/2015
Date

Representative(s)
Siemens Corporation



Daniel J. Staudt
VP, Chief IP Counsel

1/13/15
Date